2019 LEADTECK

公司簡介

Date: 11th January 2019

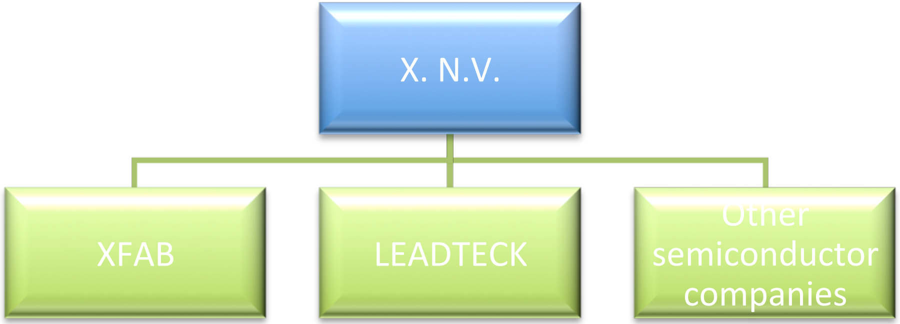
Author: Bill

公司願景

Mission Statement

To become the leader in
Niche Discrete power semiconductor
by employing
Advanced R&D with Leading Edge Technology
and producing Quality Products
that create Sustainable Added Values
to the customers.

公司架構


X. N.V.

XFAB

LEADTECK

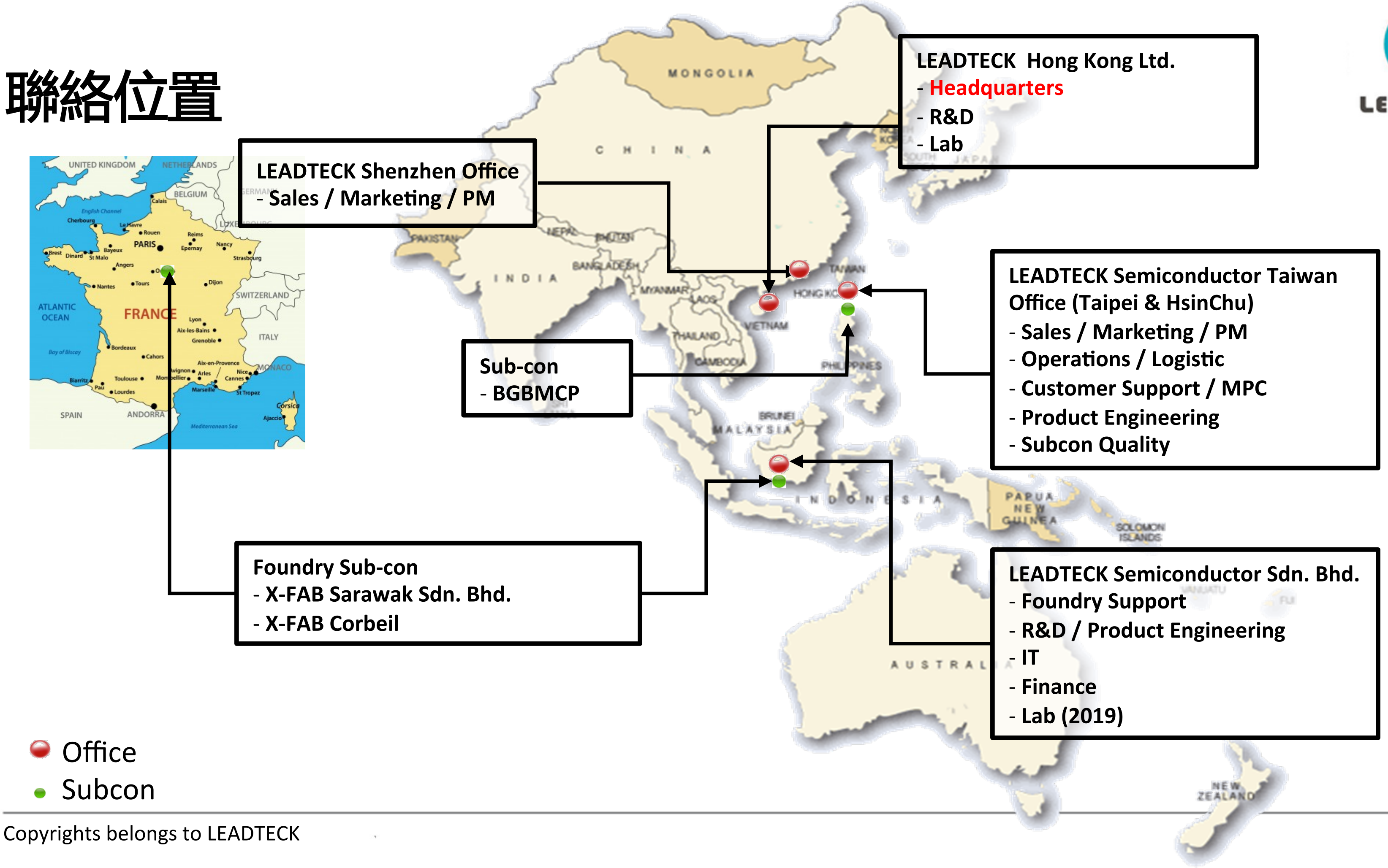
Other semiconductor companies

LEADTECK是比利時X.N.V.全資子公司，該公司擁有xtrion X-Fab矽晶圓代工公司的流通股，領泰品牌所屬公司成立於2004年，是一家專業的MOSFET芯片設計公司。為客戶提供優質晶片以及成品。

X-Fab是領泰最重要的兄弟公司。LEADTECK是公司成品战略品牌。

領泰公司在台北、新竹、馬來西亞、香港、深圳均設有分公司和聯絡網點。

聯絡位置



LEADTECK Hong Kong Ltd.
- Headquarters
- R&D
- Lab

LEADTECK Shenzhen Office
- Sales / Marketing / PM

LEADTECK Semiconductor Taiwan Office (Taipei & HsinChu)
- Sales / Marketing / PM
- Operations / Logistic
- Customer Support / MPC
- Product Engineering
- Subcon Quality

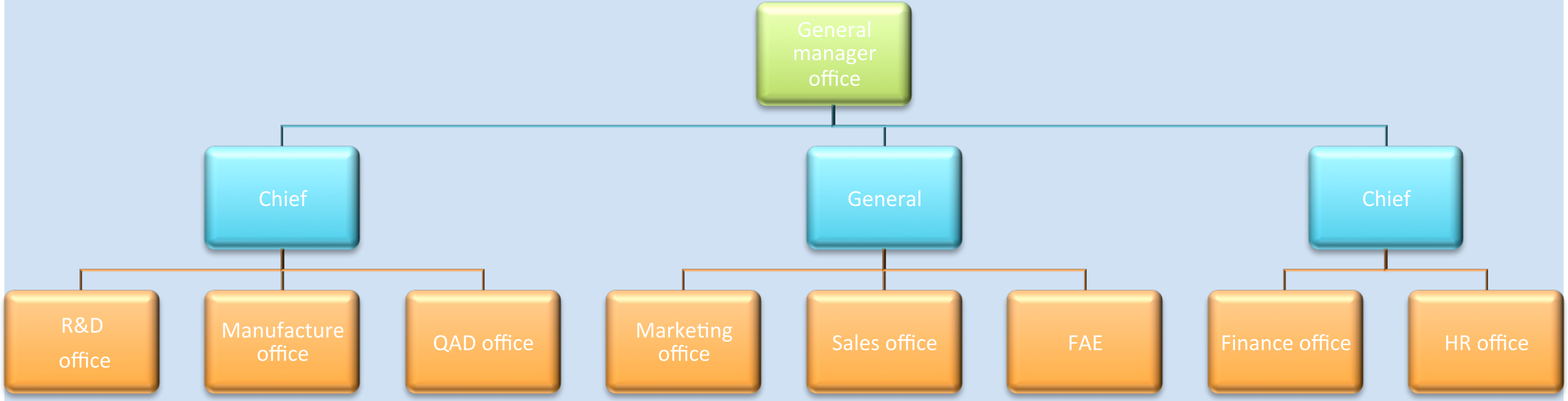
Sub-con
- BGBMCP

Foundry Sub-con
- X-FAB Sarawak Sdn. Bhd.
- X-FAB Corbeil

LEADTECK Semiconductor Sdn. Bhd.
- Foundry Support
- R&D / Product Engineering
- IT
- Finance
- Lab (2019)

🔴 Office
🟢 Subcon

組織架構



General manager office

Chief

General

Chief

R&D office

Manufacture office

QAD office

Marketing office

Sales office

FAE

Finance office

HR office

Copyrights belongs to LEADTECK

裏程碑

2004
- **Startup LEADTECK MY**

2006
- Launch production
- 1st 0.25um 8” trench MOS

2008
- **Register LEADTECK HK headquarter**
- LEADTECK Taiwan Branch
- LEADTECK Malaysia Subsidiary

2010
- Develop 2nd GEN technology
- Cell Density up to 650Mcell/in2

2012
- Launch 2nd GEN technology
- Cell Density up to 650Mcell/in2
- Engage Industrial business

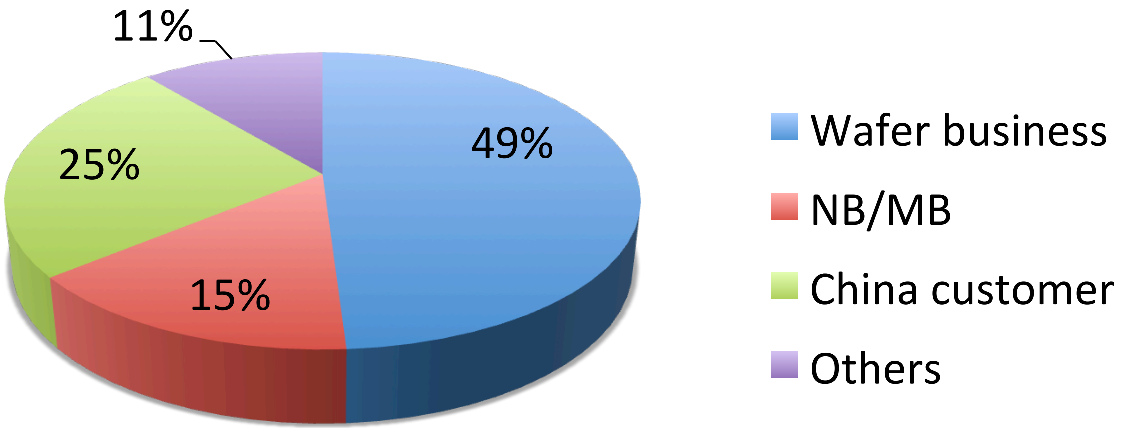
2014
- Develop SSR.
- Fast Switching ESD MOSFET

2016
- Launch Automotive MOSFET
- CSP, Low Qg MOSFET
- 3rd GEN MOSFET

2018
- Develop High Cell density technology up to 2G.
- Split Gate technology
- Power Automotive MOSFET

業務分布

2019年LEADTECK晶片與成品銷售規模約達7仟2佰萬美元，年成長率25%，2018年49% Wafer business，NB/MB(筆記本及電腦主板)15%，CHINA CUSTOMER 25%，其他11%



合作夥伴

LEADTECK

力積電

tsmc

HUA TIAN 华天科技

GOOD-ARK

gEM SERVICES

Agape

GTBF 杰群電子科技（東莞）有限公司
Great Team Backend Foundry (DongGuan), ltd

风华高科控股企业
广东风华芯电科技股份有限公司
GUANGDONG FENGHUA SEMICONDUCTOR TECHNOLOGY CO.,LTD

客戶群

AMTC
SHENZHEN MTC CO.,LTD.

vivi
Since1988

CVTE Dream-Future 视源股份

SAMSUNG

CORUN® 科力远

Haier

GoPro

Panasonic

FOXCONN 鴻海科技集團

HUAJIE®

ANKER®
POWER YOUR MOBILE LIFE

Noah诺亚舟

PHILIPS

SUNWODA 欣旺达

阿里云

ZDL
Zegna-Daidong Limited Corporation
Audio Electronic Equipment etc.

SHARP

HOBBYWING®

INTERNATIONAL HIGHPOWER 豪鹏国际

PAX
Your Payment Partner of Choice

JABIL

SAMPO 新宝
台湾品质 民族品牌

coolpad

LG
Life's Good

YANKON

SCUD 飞毛腿

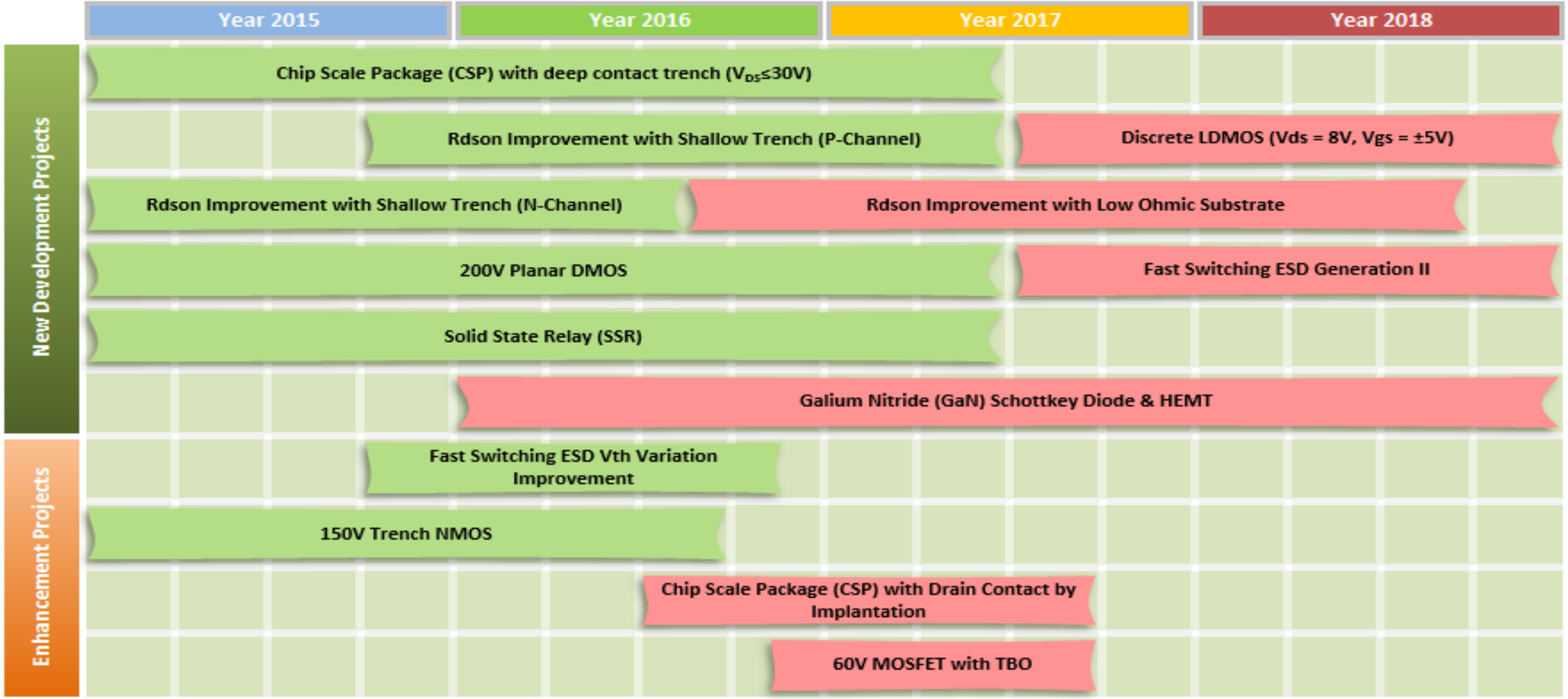
TCL

Goertek

TOPBAND 拓邦
全球领先的智能控制方案提供商

Cultraview 全锐显

ROADMAP



Year 2015

Year 2016

Year 2017

Year 2018

New Development Projects

Chip Scale Package (CSP) with deep contact trench ($V_{DS}\leq30V$)

Rdson Improvement with Shallow Trench (P-Channel)

Discrete LDMOS (Vds = 8V, Vgs = ±5V)

Rdson Improvement with Shallow Trench (N-Channel)

Rdson Improvement with Low Ohmic Substrate

200V Planar DMOS

Fast Switching ESD Generation II

Solid State Relay (SSR)

Galium Nitride (GaN) Schottkey Diode & HEMT

Enhancement Projects

Fast Switching ESD Vth Variation Improvement

150V Trench NMOS

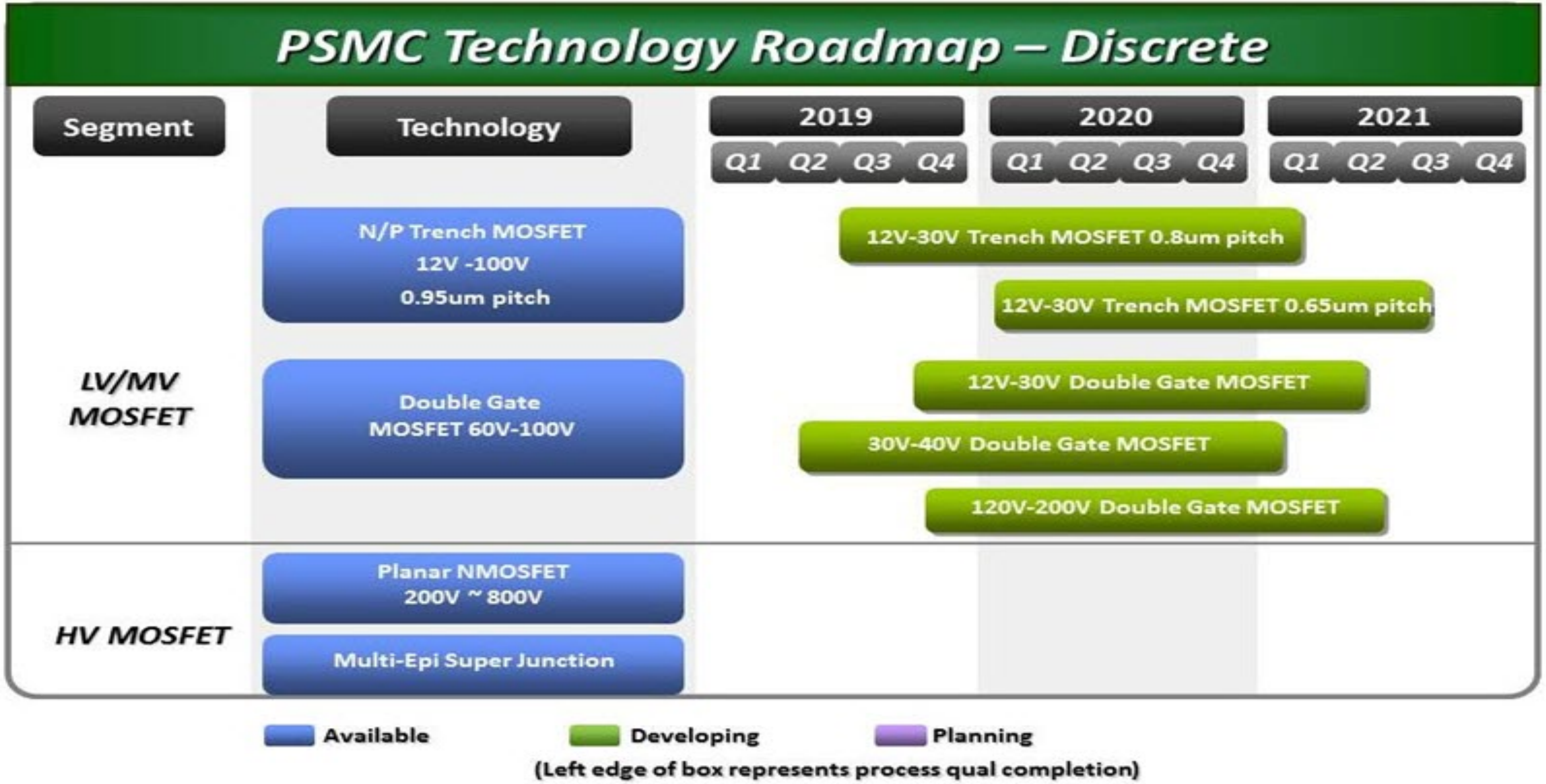
Chip Scale Package (CSP) with Drain Contact by Implantation

60V MOSFET with TBO

🟩 In Progress...

🟥 Planning...

ROADMAP



PSMC Technology Roadmap – Discrete

LV/MV MOSFET

- N/P Trench MOSFET 12V -100V 0.95um pitch
- Double Gate MOSFET 60V-100V

12V-30V Trench MOSFET 0.8um pitch

12V-30V Trench MOSFET 0.65um pitch

12V-30V Double Gate MOSFET

30V-40V Double Gate MOSFET

120V-200V Double Gate MOSFET

HV MOSFET

- Planar NMOSFET 200V ~ 800V
- Multi-Epi Super Junction

🟦 Available 🟩 Developing 🟪 Planning

(Left edge of box represents process qual completion)

技術工藝

Fabless Business Model：8”Sub-Micron

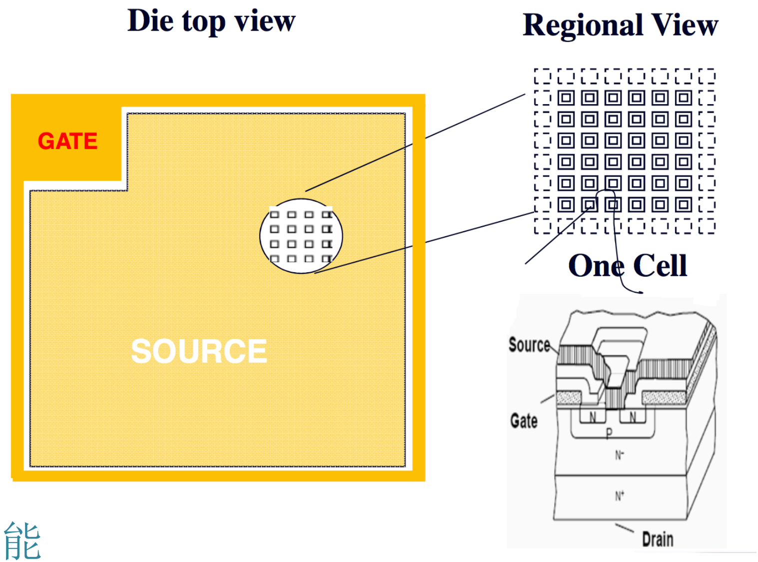
- 使用8英寸晶片製造產品
- 高可靠性，相對低的成本
- 利用先進設備平台使用先進生產工藝

Advanced Process Technology

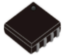
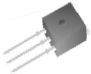
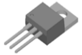
- Wide voltage range寬電壓範圍
- 12VDS to 200VDS rated MOSFETS
- Low on-resistance低阻抗，低功耗
- 0.12 mΩ/cm2，world class RDS Area
- 253Mcell/in2 closed cell density
- Excellent switching performance 優異的產品性能
- World class RG(down to 0.25Ω),Qg,body diode recovery,CRSS/CISS ratio

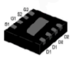
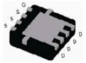
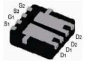
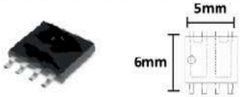
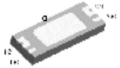
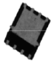
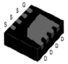
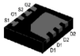
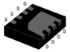
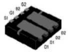
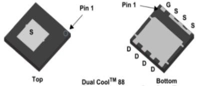
Advances Packaging

- Shipping>100MU/Mo of industry standard packages工業級封裝
- Developing new high performance packages開發更新的封裝

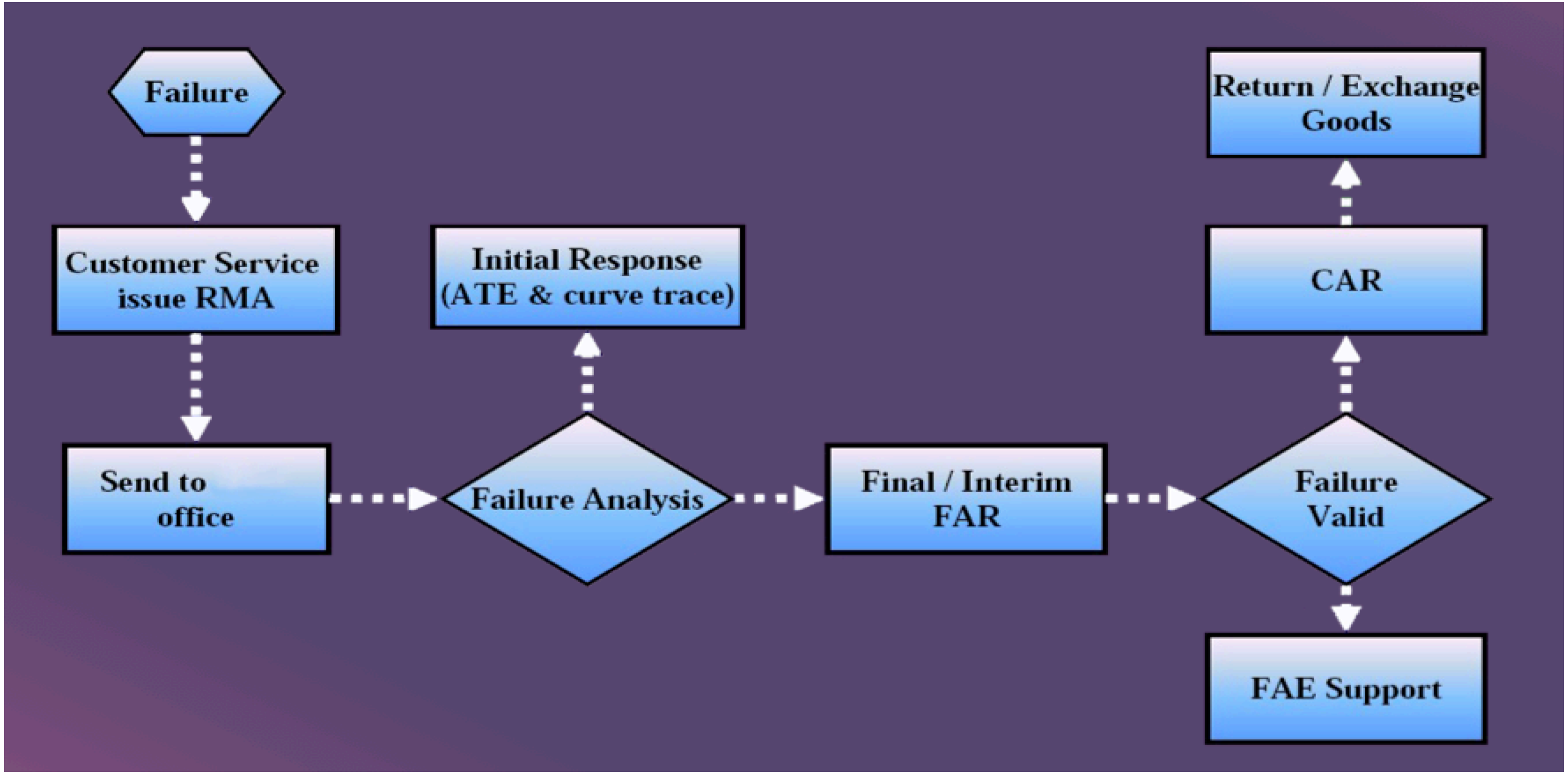


封裝品種

 SOT-23	 J2928-8	 SOT-223
 TSOP6	 TO-251	 SOT-262
 SOP-8  TSSOP-8	 TO-263	 SOT-323  SOT-363
 TO-220  TO-220F	 TO-252 3L  TO-252 4L	 SOT-523  SOT-563
 TO-247	 SOT-89	 SOT-723

 DFN2x2 6L  DFN2x2 8L	 DFN(S)3.3x3.3 Single  DFN(S)3.3x3.3 dual	 LF-PAK56D
 DFN3x2	 DFN5x2	
 DFN3x3 NEP	 DFN5x6	
 DFN3x3 Single  DFN3x3 dual	 Power BGA	
 DFN3.3x3.3 Single  DFN3.3x3.3 dual	 Dual Cool 2015	

失效分析流程


Failure
Customer Service issue RMA
Send to office
Failure Analysis
Initial Response (ATE & curve trace)
Final / Interim FAR
Failure Valid
CAR
Return / Exchange Goods
FAE Support

品質政策

品質焦點：

1.顧客滿意

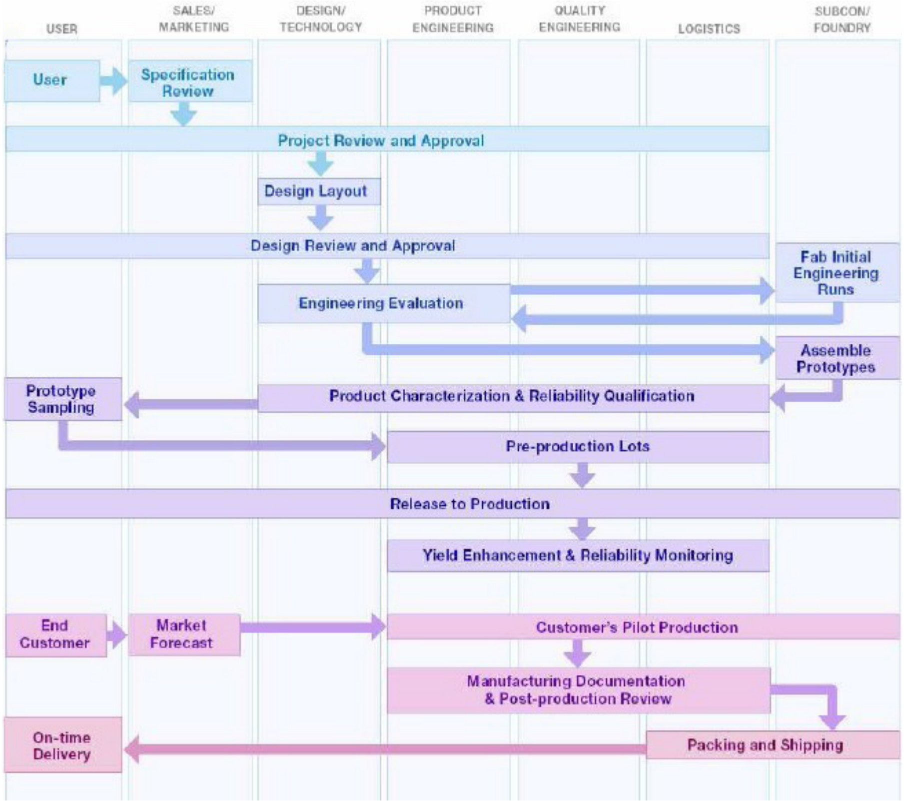
LEADTECK把顧客滿意放在第壹位，因為我們知道我們的成功取決於我們滿足顧客的能力。

2.持續改進

所有LEADTECK員工都明白，我們必須繼續提高我們相對於競爭對手的競爭優勢。

3.全面參與

公司各級參與產品質量和服務建設。



THANK YOU